

1W, 2512, Low Resistance Chip Resistor (Lead / Halogen Free)

1. Scope

This specification applies to6.4mm x 3.2mm size 1W, fixed thick film low resistance value chip resistors rectangular type.

2. Type Designation

RLT3264 - 6 -

$$(1)$$
 (2) (3) (4)

Where (1) Size No.

(2) Power Rating:

6 = 1W

(3) Resistance value: Refer to paragraph 4-1

For example --

Four digits of number

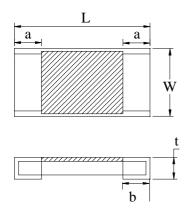
 $R100 = 0.1\Omega$

 $1R00 = 1.0\Omega$

The "R" shall be used as a decimal point

(4) Resistance tolerance: refer to paragraph 4-1

3. Outline Dimensions



Code Letter	Dimension
L	6.30 ± 0.15
W	3.20 ± 0.15
t	0.55 ± 0.15
а	0.60 ± 0.20
b	0.60 ± 0.20

Unit : mm

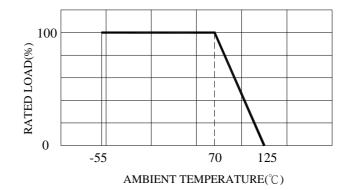


4. Ratings

Power Rating*	1 V	1 W	
Resistance Tolerance	1%(F), 2%(1%(F), 2%(G), 5%(J)	
Resistance Range	$0.05\Omega \sim < 0.1\Omega$	0.1Ω ~ 1Ω	
Temperature Coefficient of Resistance(ppm/°C)	0 ~ +200	0 ~ +100	

Note*:

Power Rating is based on continuous full load operation at rated ambient temperature of 70° C. For resistor operated at ambient temperature in excess of 70° C, the maximum load shall be derated in accordance with the following curve.



4-2 Rated Voltage

The d.c. or a.c. r.m.s. voltage shall be calculated from the following expression

 $V = \sqrt{P \times R}$

Where V : Rated voltage (V)

- P : Rated power (W)
- R : Nominal resistance (Ω)
- 4-3 Operating and Storage Temperature Range -55 to +125 °C

SPECIFICATION FOR APPROVAL

DOCUMENT : SRK860000NH REVISION : A1 : 3 OF 9

PAGE

5. Marking

Each Resistor is marked with 4 digits code on the protective coating to designate to the nominal resistance value.

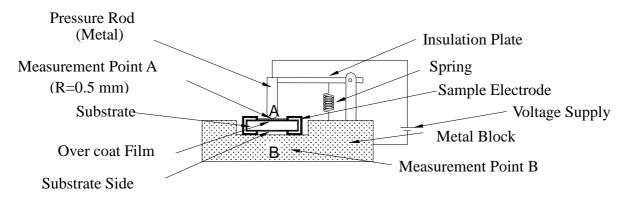
 $0.05\, \cong\, R\, \cong 1\Omega$, Marking 4 digits

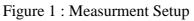
$$\begin{array}{rcl} \text{EX} & 0.05\Omega \rightarrow \mathbb{R}050 & , & 0.1\Omega \rightarrow \mathbb{R}100 \\ & 1.00\Omega \rightarrow \mathbb{R}00 \end{array}$$

6. Characteristics

6-1 Electrical

Item	Specification and Requirement	Test Method (JIS 5201)
Temperature Coefficient of Resistance (TCR)	As follow table 1.	Room temperature Room temperature+100℃
Short Time Overload	\triangle R:±1.0% Without damage by flashover, spark, arcing, burning or breakdown	 Applied voltage: 2.5 x rated voltage Test time: 5 seconds
Insulation Resistance	Over 100 MΩ on Overcoat layer face up Over 1,000 MΩ on Substrate side face up	 Setup as figure 1 Test voltage: 100V_{DC}±15V_{DC} Test time: 60 + 10 / - 0 seconds
Voltage Proof	Resistance range:±1.0% Without damage by flashover, spark, arcing, burning or breakdown	 Setup as figure 1 Test voltage: 400V_{AC}(rms.) Test time: 60 + 10 / - 0 seconds







DOCUMENT : SRK860000NH REVISION : A1

PAGE : 4 OF 9

Item	Specification and Requirement	Test Method (JIS 5201)
Solderability	The surface of terminal immersed shall be minimum of 95% covered with a new coating of solder	Solder bath: After immersing in flux, dip in 245 ± 5°C molten solder bath for 2 ± 0.5 seconds
Resistance to Solder Heat	\triangle R: ± 1.0% Without distinct deformation in appearance	 Pre-heat: 100~110°C for 30 seconds Immersed at solder bath of 270 ± 5°C for 10 ± 1 seconds Measuring resistance 1 hour after test
Bending Test	\triangle R: ± 1.0% Without mechanical damage such as break	Bending value: 1 mm for 30 ± 1 seconds
Solvent Resistance	Without mechanical and distinct damage in appearance	 (1) Solvent: Trichloroethane or Isopropyl alcohol (2) Immersed in solvent at room temperature for 300 seconds



DOCUMENT : SRK860000NH REVISION : A1

PAGE : 5 OF 9

6-3 Endurance		
Item	Specification and Requirement	Test Method (JIS 5201)
Rapid Change of Temperature	△ R:±1.0% Without distinct damage in appearance	 (1) Repeat 5 cycle as follow: (-55 ± 3°C,30minutes) →(Room temperature, 2~3 minutes) →(+125 ± 2°C,30minutes) →(Room temperature 2~3 minutes) (2) Measuring resistance 1 hour after test
Moisture with Load	\triangle R: ±5.0% Without distinct damage in appearance	(1) Environment condition: $40 \pm 2^{\circ}C,90 \sim 95\%$ RH (2) Applied Voltage: rated voltage (3) Test period: (1.5 hour ON) \rightarrow (0.5 hour OFF) cycled for total 1,000 + 48 / - 0 hours (4) Measuring resistance 1 hour after test
Load Life	 △ R: ±5.0% Without distinct damage in appearance 	 (1) Test temperature: 70 ± 3°C (2) Applied Voltage: rated voltage (3) Test period: (1.5 hour ON) →(0.5 hour OFF) cycled for total 1,000 + 48 / - 0 hours (4) Measuring resistance 1 hour after test
Low Temperature Store	\triangle R: ± 5.0% Without distinct damage in appearance	 (1) Store temperature: -55 ± 3°C for total 1,000 + 48 / - 0 hours (2) Measuring resistance 1 hour after test
High Temperature Store	\triangle R: ± 5.0% Without distinct damage in appearance	 (1) Store temperature: +125 ± 2°C for total 1,000 + 48 / - 0 hours (2) Measuring resistance 1 hour after test

SPECIFICATION FOR APPROVAL

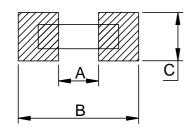
DOCUMENT : SRK860000NH

REVISION : A1

PAGE

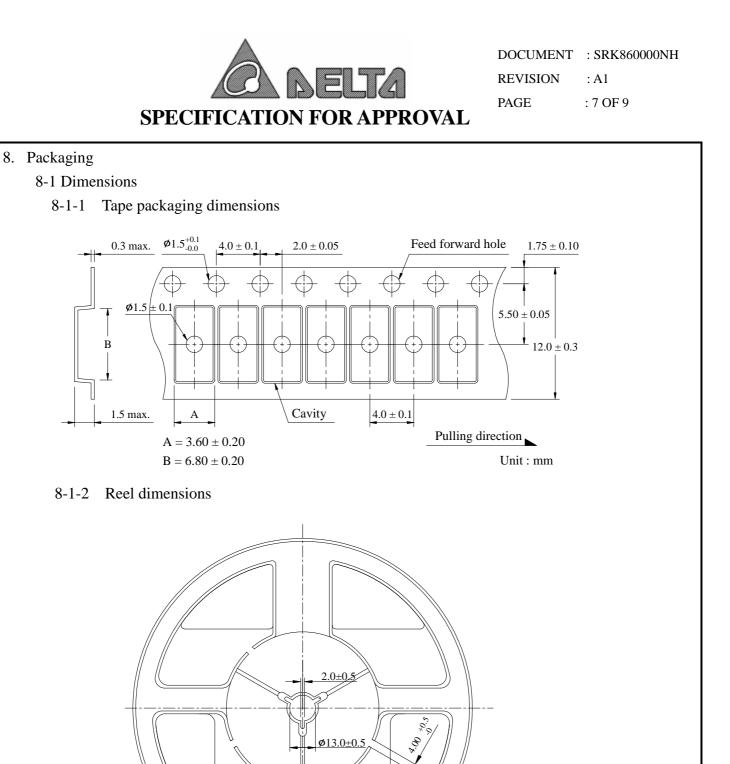
: 6 OF 9

7. Recommend Land Pattern Dimensions



4.8~5.1
7.9~8.1
2.9~3.2





Ø178.0±2.0 Ø60.2±0.5

Unit : mm

16.0±0.2

13.2±1.5

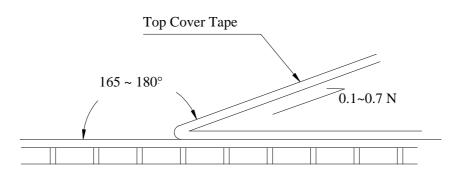
SPECIFICATION FOR APPROVAL

DOCUMENT: SRK860000NHREVISION: A1PAGE: 8 OF 9

8-2 Peel force of top cover tape

The peel speed shall be about 300 mm/min.

The peel force of top cover tape shall be between 0.1 to 0.7 N.



8-3 Numbers of taping 2,000 pieces /reel

8-4 Label making

The following items shall be marked on the reel.

- (1) Type designation.
- (2) Quantity
- (3) Manufacturing date code
- (4) Manufacturer's name



DOCUMENT: SRK860000NHREVISION: A1PAGE: 9 OF 9

9. Carenote

- 9-1 Care note for storage
 - (1) Chip resistor shall be stored in a room where temperature and humidity must be controlled. (temperature 5 to 35°C, humidity 45 to 85% RH) However, a humidity keep it low, as it is possible.
 - (2) Chip resistor shall be stored as direct sunshine doesn't hit on it.
 - (3) Chip resistor shall be stored with no moisture, dust, a material that will make solderability inferior, and a harmful gas (Chloridation hydrogen, sulfurous acid gas, and sulfuration hydrogen)
- 9-2 Carenote for operating and handling
 - (1) It is necessary to protect the edge and protection coat of resistors from mechanical stress.
 - (2) Handle with care when printing circuit board (PCB) is divided or fixed on support body, because bending of printing circuit board (PCB) mounting will make mechanical stress for resistors.
 - (3) Resistors shall be used with in rated range shown in specification. Especially, if voltage more than specified value will be loaded to resistor, there is a case it will make damage for machine because of temperature rise depending on generating of heat, and increase resistance value or breaks.
 - (4) In case that resistor is loaded a rated voltage, it is necessary to confirms temperature of a resistor and to reduce a load power according to load reduction curve, because a temperature rise of a resistor depends on influence of heat from mounting density and neighboring element.
 - (5) Observe Limiting element voltage and maximum overload voltage specified in each specification
 - (6) If there is possibility that a large voltage (pulse voltage, shock voltage) charge to resistor, it is necessary that operating condition shall be set up before use.